MODEL I	NO.	:	G1601FP161GG-001

ISSUED DATE: 2017-12-01

VERSION: A0

■ Preliminary Specification □ Final Product Specification

Customer	:	

Approved by	Notes

GVO Confirmed:

Prepared by	Checked by	Approved by
赵天亨	陈水礼	\$1.55g.

This technical specification is subjected to change without notice.



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■ 〒 ★ 및 KUNSHAN GOVISIONOX OPTOELECTRONICS CO., LTD G1601FP161GG-001 Record of Revision

Rev	Issue Date	Description	Editor
A0	2017-12-01	Draft	Zhao Tianyu



1 General Specifications

	Feature	Spec	Remark
	Screen Size (inch)	6.01	
	Display Mode	AMOLED	
	Resolution(dot)	1080(W)×2160(H)	
	Active Area(mm)	68.256(W)×136.512 (H)	
Display Spec	Pixel Pitch (um)	63.2 (W)×63.2(H)	
	Technology Type	LTPS	
	Color Depth	16.7M	
	Interface	MIPI 4LANE	
	Surface Treatment	Hard Coating	
	With TP/Without TP	With TP(on Cell)	
Mechanical Characteristi cs	Module Outline Dimension(W x H x D) (mm)	70.066(W)x142.297(H)x0.773(D)	
	Weight (g)	TBD	
Electronic	Driver IC(Type)	RM69298	
2.000.01.10	Touch IC(Type)	GT1151	

Note 1: Requirements on Environmental Protection: RoHS.



Input/output Terminals

2.1 Main FPC Pin Assignment

FPC connector: BM24-50DS/2-0.35V(51) (Socket), B-TO-B Connector.

Main board recommended connector: BM24-50DP/2-0.35V(51) (Header), B-TO-B Connector.

No	Symbol	I/O	Description	
1	GND	GND	Ground	
2	ELVSS	Р	Negative power supply for EL	
3	VPP	Р	Power supply for MTP Programming or Erase. If it is not used, please let it open.	
4	ELVSS	Р	Negative power supply for EL	
5	GND	GND	Ground	
6	ELVSS	Р	Negative power supply for EL	
7	D3N	Ι	MIPI data lane	
8	GND	GND	Ground	
9	D3P	Ι	MIPI data lane	
10	ELVDD	Р	Positive power supply for EL	
11	GND	GND	Ground	
12	ELVDD	Р	Positive power supply for EL	
13	D0N	I	MIPI data lane	
14	ELVDD	P	Positive power supply for EL	
15	D0P	I	MIPI data lane	
16	GND	GND	Ground	
17	GND	GND	Ground	
18	RESX	Ι	Display reset. Active low.	
19	CLKN	Ι	MIPI clock lane	
20	AVDD_EN	0	Power IC enable control pin	
21	CLKP	I	MIPI clock lane	
22	SWIRE	0	Control signal for power IC	
23	GND	GND	Ground	
24	ERR_FG	0	Error status of MIPI's HSDT	
25	D1N	Ι	MIPI data lane	

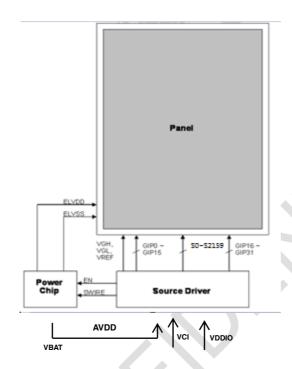


ae Ju	T & RONSHAN GOVISIONOX OF TOLLECTRONICS CO., LID G1001FF 101GG-001					
26	PCD	I	panel crack detection			
27	D1P	I	MIPI data lane			
28	TE	I	Sync Signal for preventing Tearing Effect			
29	GND	GND	GND Ground			
30	GND	GND	Ground			
31	D2N	I	MIPI data lane			
32	TSP_AVDD_3.3V	Р	Analog Power for TP			
33	D2P	I	MIPI data lane			
34	AVDD	Р	Power supply for Analog system			
35	GND	GND	Ground			
36	VCI	Р	Power supply for display analog circuits			
37	TSP_DVDD_1.8V	Р	Power supply for TP logic circuits			
20		Р	Power supply for interface system except			
30	VDDIO		MIPI/MDDI interface			
39	TSP_TA	NC				
40	GND	GND	Ground			
41	TSP_INT	I	Interrupt signal for TP			
42	F_SCLK	I	Flash signal			
43	TSP_SCL	I	SCL pin for TP			
44	F_CSN	I	Flash signal			
45	TSP_SDA	I/O	SDA pin for TP			
46	F_IO<0>	I/O	Flash signal			
47	TSP_RESET	I	Reset Pin for TP, Active low.			
48	F_IO<1>	I/O	Flash signal			
49	GND	GND	Ground			
50	GND	GND	Ground			

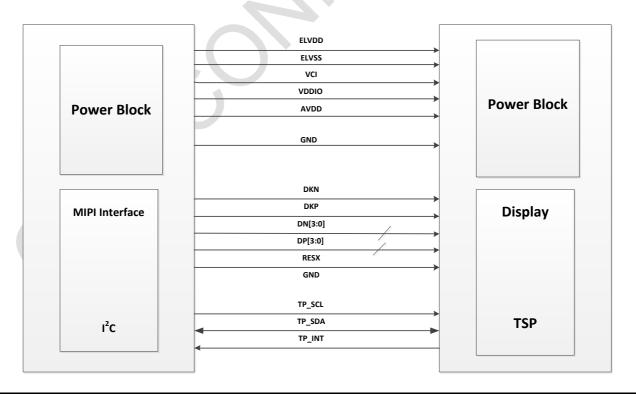
Note: I=Input; O=Output; P=Power; I/O=Input / Output



2.2 Circuit block diagram (Display)



2.3 MCU and Display Module Interface Configuration





3 Absolute Maximum Ratings

3.1 Driving AMOLED Panel

Maximum Ratings (Voltage Referenced to VSS) Vss=0V, Ta=25℃

Item	Symbol	MIN	MAX	Unit
Analog Power supply	VCI	-0.3	+5.5	V
Logic Power supply	VDDIO	-0.3	+5.5	V
Positive Power Input	ELVDD	-	+5.0	V
Negative Power Input	ELVSS	-5.0		V

Note: Functional operation should satisfy the limits in the Electrical Characteristics tables or Pin Description section. If the module exceeds the absolute maximum ratings, permanent damage may occur. Besides, if the module is operated with the absolute maximum ratings for a long time, the reliability may also drop.

4 Electrical Characteristics

4.1 Driving AMOLED Panel

Item		Symbol	MIN	TYP	MAX	Unit
Logic Power:	supply	VDDIO	1.65	1.80	3.3	V
Analog Powe	117	VCI	2.5	2.80	3.60	V
ELVDD Supp	ly Voltage	ELVDD	4.55	4.60	4.65	V
ELVSS Suppl	ly Voltage	ELVSS	-5	-3	-	V
Input Signal	High Level	VIH	0.80*VDDIO	-	VDDIO	V
Voltage	Low Level	VIL	0.00	-	0.20*VDDIO	V
Output	High Level	VOH	0.80*VDDIO	-	VDDIO	V
Signal Voltage	Low Level	VOL	0.00	-	0.20*VDDIO	V
		I _{ELVDD} /I _{ELVSS}	-	TBD	TBD	mA
No	ormal	I _{VCI}	-	TBD	TBD	mA
INO	omai	I _{VDDIO}	-	TBD	TBD	mA
		l _{avdd}	-	TBD	TBD	mA
Stand-by		I _{VCI}	-	TBD	TBD	uA
		I _{VDDIO}	-	TBD	TBD	uA

Ta=25°C

Note1: The input digital voltage is the I/O reference voltage.

Note2: VDDIO usually ranges from 1.65V to 3.3 V. If VDDIO is changed, the remaining voltage needs to be changed to the same voltage as VDDIO.

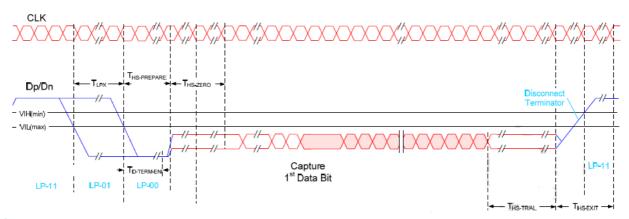
Note3: Under full white pattern, Video Mode 60 Hz.

Note4: 60Hz command mode at 800 Mbps.

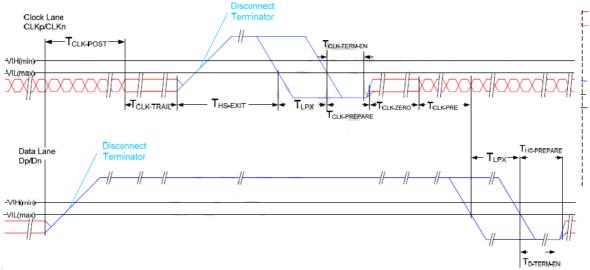


AC Characteristics

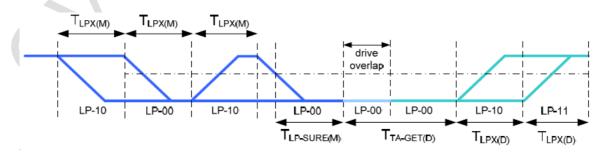
5.1 MIPI Interface Characteristics HS Data Transmission Burst



HS clock transmission

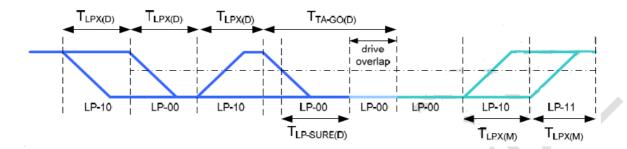


Turnaround Procedure





Bus turnaround (BAT) from MPU to display module timing



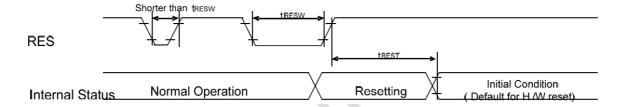
Timing Parameters:

Parameter	Description	Min	Тур	Max	Unit
T _{CLK-POST}	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of T	60ns + 52*UI			ns
T _{CLK-TRAIL}	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns
T _{HS-EXIT}	Time that the transmitter drives LP-11 following a HS burst.	300			ns
T _{CLK-TERM-EN}	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses V _{IL,MAX} .	Time for Dn to reach V _{TERM-EN}		38	ns
T _{CLK-PREPARE}	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns
T _{CLK-PRE}	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8			UI
T _{CLK-PREPARE} + T _{CLK-ZERO}	T _{CLK-PREPARE} + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns
T _{D-TERM-EN}	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses V _{IL,MAX} .	Time for Dn to reach V _{TERM-EN}		35 ns +4*UI	
T _{HS-PREPARE}	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	40ns + 4*UI		85 ns + 6*UI	ns
T _{HS-PREPARE} + T _{HS-ZERO}	T _{HS-PREPARE} + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	145ns + 10*UI			ns
T _{HS-TRAIL}	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	60ns + 4*UI			ns



I	Parameter	Description	Min	Тур	Max	Unit	Notes
•	T _{LPX(M)}	Transmitted length of any Low-Power state period of MCU to display module	50		150	ns	1,2
•	T _{TA-SURE(M)}	Time that the display module waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	T _{LPX(M)}		2*T _{LPX(M)}	ns	2
	T _{LPX(D)}	Transmitted length of any Low-Power state period of display module to MCU	50		150	ns	1,2
ľ	T _{TA-GET(D)}	Time that the display module drives the Bridge state (LP-00) after accepting control during a Link Turnaround.		5*T _{LPX(D)}		ns	2
•	T _{TA-GO(D)}	Time that the display module drives the Bridge state (LP-00) before releasing control during a Link Turnaround.		4*T _{LPX(D)}		ns	2
	T _{TA-SURE(D)}	Time that the MPU waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	T _{LPX(D)}		2*T _{LPX(D)}	ns	2

5.2 Display RESET Timing Characteristics Reset input timing:



VDDIO=1.65 to 3.3V, VDD=2.7 to 3.6V, AGND=DGND=0V, Ta=-40 to 85° C

Timing Parameters

Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
t _{RESW}	*1) Reset low pulse width	RESX	10	-	-	-	μs
	*2\ Decet complete time	-	-	-	5	When reset applied during Sleep in mode	ms
t _{REST}	*2) Reset complete time	-		-	120	When reset applied during Sleep out mode	ms

Note1. Spike caused by an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5µs	Reset Rejected
Longer than 10μs	Reset
Between 5μs and 10μs	Reset starts (It depends on voltage and temperature condition.)

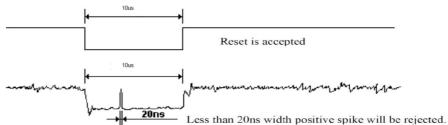
Note 2. During the resetting period, the display will be blank (The display is entering blanking sequence,



whose maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains blank in Sleep In –mode) and then return to Default condition for H/W reset.

Note 3. During Reset Complete Time, data in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (tREST) within 5ms after a rising edge of RESX.

Note 4. Spike Rejection also applies during a valid reset pulse as shown below:



Note 5. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

5.3 TE Timing Characteristics

Mode1, The Tearing Effect Output line consists of V-Blanking information only.



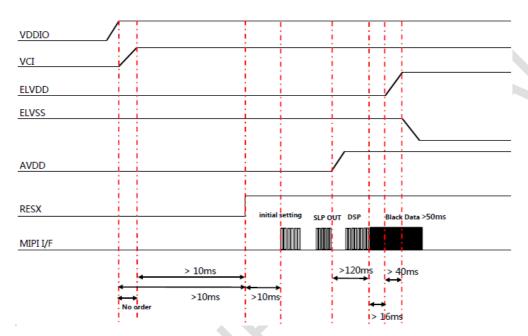
Tvdh = The display is not updated from the frame memory. Tvdl = The display is updated from the frame memory.



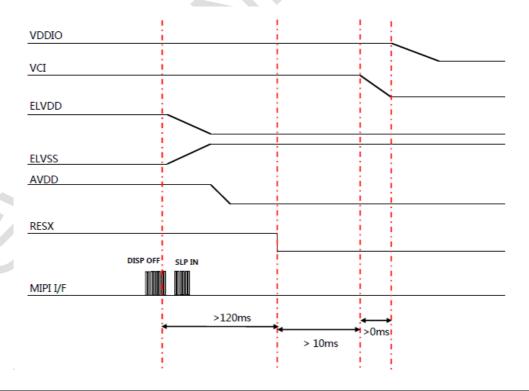
Recommended Operating Sequence

6.1 Display Power on / off Sequence

6.1.1 Power On Sequence



6.1.2 Power Off Sequence





6.2 Brightness control

Use "command 5100h, data xxh" to adjust the Manual Brightness value of the display: In principle relationship is that 00h value means the lowest brightness and FFh value means the highest brightness.

Inot/Dara	DAM	Addr	ess	Data Tura	Description	
Inst/Para	R/W	MIPI	Other	Date Type	Description	
BRTCTRL	W	51h	5100h	Hex	Value form 0~255(FF)	



■ 〒 ★ 및 KUNSHAN GOVISIONOX OPTOELECTRONICS CO., LTD G1601FP161GG-001 7 Optical Characteristics Optical Specification

Item		Symbol	Condition	Min	Тур	Max	Unit	Remark	
		θТ		80	ı				
Viou Anglo	View Angle		CR≥10	80	-		Dograd	Note 2	
View Angle		θL	CR210	80	-		Degree	Test Equipment: CS2000A	
		θR		80	-				
Contrast Rat	Contrast Ratio		θ=0°	100000				Note1 Note3 Test Equipment: CS2000A	
		T _{ON}						Note1	
Response Ti	me	T _{OFF}	25 ℃		(1	ms	Note4 Test Equipment: Admesy MSE	
	White	Х		(0.280)	(0.300)	(0.320)			
	VVIIIC	у		(0.295)	(0.315)	(0.335)			
	Red	Х		(0.625)	(0.655)	(0.685)		Test Equipment: CS2000A	
Chromaticity		у		(0.315)	(0.345)	(0.375)		Note: Chromaticity	
Chilomaticity	Green	х		(0.210)	(0.250)	(0.290)		can be modified	
	Green	у		(0.670)	(0.710)	(0.750)		according to customer demand	
	Blue	х		(0.105)	(0.135)	(0.165)		a contains	
	Diue	у		(0.030)	(0.060)	(0.090)			
Uniformity		U		75			%	Note1 Note6 Test Equipment: CS2000A	
NTSC				90	100		%	Note5	
Luminance		L	Normal	365	430	495	Cd/m ²	Note1 Note7 Test Equipment: CS2000A	
Cross-talk						1.5	%	Note8 Test Equipment: CS2000A	



					Gamma=2.2±0.2
Gamma		2.0	2.2	2.4	Test Equipment: CS2000A

Test Conditions:

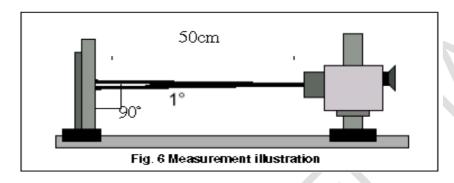
the ambient temperature is 25°C.

1. The test systems refer to Note1 and Note2.



Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. The optical properties are measured at the center point of the AMOLED screen. All input terminals AMOLED panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system.

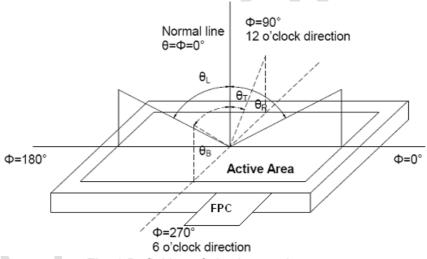


Fig. 1 Definition of viewing angle



Note 3: Definition of contrast ratio

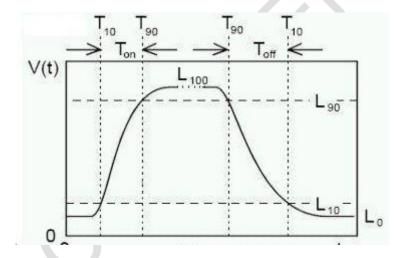
 $Contrast\ ratio(CR) = \frac{Lu\, min\, ance\ measured\ when\ LCD\ is\ on\ the\ "white"\ state}{Lu\, min\, ance\ measured\ when\ LCD\ is\ on\ the\ "Black"\ state}$

"White state ": A state where the AMOLED should be driven by Vwhite.

"Black state": A state where the AMOLED should be driven by Vblack.

Note 4: Definition of response time

The response time is defined as the AMOLED optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changing from 10% to 90%. And fall time (T_{OFF}) is the time between photo detector output intensity changing from 90% to 10%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates are measured at the center point of AMOLED.



Note 6: Definition of luminance uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity(U) = Lmin/Lmax

L----- Active area length W----- Active area width

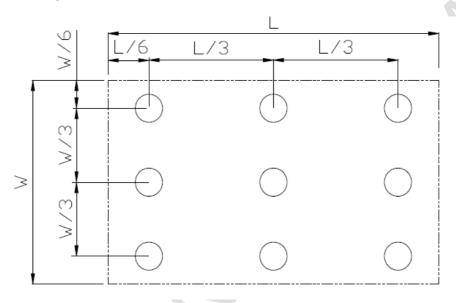


Fig. 2 Definition of uniformity

Lmax: The measured maximum luminance of all measurement position.

Lmin: The measured minimum luminance of all measurement position.

Note 7: Definition of luminance:

Measure the luminance of white state at the center point.

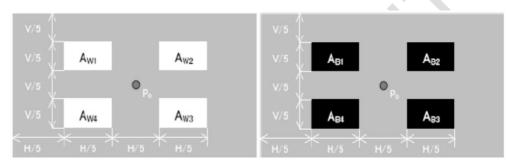
Note 8: Cross Talk

A. Measure luminance at the position, P0.

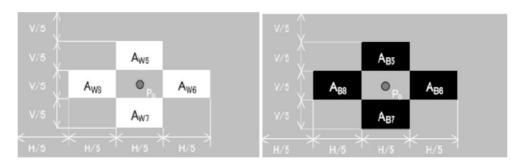
B. Calculate cross talk as below equation.



$$\begin{split} L_{W_OFF} &= \frac{L_{W1} + L_{W2} + L_{W3} + L_{W4}}{4} \\ L_{B_OFF} &= \frac{L_{B1} + L_{B2} + L_{B3} + L_{B4}}{4} \\ crosstalk &= \frac{|L_{Wi_ON} - L_{W_OFF}|}{L_{W_OFF}} \times 100\% \qquad (i = 5 \text{ to } 8) \\ crosstalk &= \frac{|L_{Bi_ON} - L_{B_OFF}|}{L_{B_OFF}} \times 100\% \qquad (i = 5 \text{ to } 8) \end{split}$$



(a) Lw_OFF, LB_OFF measuring pattern



(b) L_{W_ON} , L_{B_ON} measuring pattern



8 Environmental / Reliability Test

No	Test Item	Condition	Remark
1	High Temperature Operation	+70℃, 120hrs	According to the customer request
2	Low Temperature Operation	-20℃, 120hrs	According to the customer request
3	High Temperature Storage	+80℃, 120hrs	According to the customer request
4	Low Temperature Storage	-30℃, 120hrs	According to the customer request
5	High Temperature & High Humidity Operation	60℃, 90% RH,120hrs	According to the customer request
6	High Temperature & High Humidity Storage	60℃, 90% RH,120hrs	According to the customer request
7	Thermal Shock (Non-operation)	-30°C (30 min)~+70°C (30 min), Change time:10min, 30Cycles	According to the customer request
8	Electro Static Discharge (Operation)	C=150pF, R=330 Ω , 5points/panel Air:±8KV, 5times; Contact:±4KV, 5 times; (Environment: 15° \mathbb{C} ~35° \mathbb{C} , 30%~60%, 86Kpa~106Kpa).	IEC61000-4-2 GB/T17626.2



9 Quality Level

9.1 AMOLED Module of Characteristic Inspection

The environmental condition and visual inspection shall be conducted as below:

(1) Ambient temperature: 23± 3°C

(2) Humidity: 55 ± 10%RH

(3) Ambient light intensity of visual inspection: 800 ~ 1200 lux

(4) Ambient light intensity of function inspection: ≤200lux

(5) Viewing Distance: 30 ± 5cm

(6) Viewing angle (tolerance): the front side 45° (Z) $\pm 15^{\circ}$

(7) Inspection time: 10 ±5 sec

9.2 Sampling Procedures for each item acceptance table

Defect type	Sampling Procedures	AQL
Major defect	GB/T2828.1-2003 Inspection level II normal inspection single sample inspection	0.65
Minor defect	GB/T2828.1-2003 Inspection level II normal inspection single sample inspection	1.0

Major defect:

Any defect may result in functional failure, or reduce the usability of product for its purpose. For example, electrical failure, deformation and etc.

Minor defect

A defect does not reduce the usability of product for its intended purpose and un-uniformity, such as dot defect and etc.

The criteria on major and/or minor judgment will be according with the classification of defects.

9.3 Inspection Item

0.0	mopcodon item					
No	Item	Area		Criterion of Defect		Defec t type
			Туре	DS	Acceptabl e number	
4	Det Defect	ot Defect AA	Bright Dot	≥10mm	0	
1	Dot Defect		Dark Dot	≥10mm	4	Minor
			Dark Dot (≥two	≥10mm	2	IVIIIIOI



The second secon	40110101		HOMOO OO., LI	<u> </u>	TEPIDIGG-00			
		connections)			.			
No Display	AA		1		Not allowed	Fatal		
Abnormal Display	AA		1		Not allowed	Fatal		
Normally white	AA		/ Not allowed					
			Bright line					
		single line	Dark lin	е	Not allowed			
Line Defect	A A	NAVILIO I DI DO	Bright lir	ne	Not	F-4-1		
Line Detect	AA	Multiple lines	Dark lin	е	Not allowed	Fatal		
		Holf Line	Bright lin	ne	Not allowed			
		пан-ыне	Dark lin	е	Not allowed			
Image sticking	AA	Switch to the ne			mage of the	Major		
Color & Edge Mura	AA	See limit	sample(under ful	l white scr	reen)	Major		
Color crast	AA	See limit	sample(under ful	I white scr	reen)	Major		
Water Ripple	AA		Not allowed	d		Major		
Other mura(Low gray-scale white spot、S-Line Mura)	AA	,		,		Major		
TP	AA	TP	function NG		Not allowed	Fatal		
Glass crack	AA, OA		1		Not allowed	Fatal		
Screen bump	AA、OA	Encap surface is	s not allowed and assembly	I LTPS do	es not affect	Major		
		W (mm)	L (mm)	DS (mm)	Acceptabl e number			
Line cofe sta /lia/st		W≤0.03	-		Ignore]		
visible)	AA	0.03 <w≤0.05< td=""><td>L≤5.0</td><td>≥10</td><td>2</td><td>Minor</td></w≤0.05<>	L≤5.0	≥10	2	Minor		
		0.05 <w< td=""><td>-</td><td>-</td><td>0</td><td>]</td></w<>	-	-	0]		
		-	L>5.0	-	0			
Point sefects	AA	D (mm)	DS (mm	1)	Acceptabl e number	Minor		
(light visible)		D≤0.1	1		Ignore			
	No Display Abnormal Display Normally white Line Defect Image sticking Color & Edge Mura Color crast Water Ripple Other mura(Low gray-scale white spot、S-Line Mura) TP Glass crack Screen bump Line sefects (light visible)	No Display AA Abnormal Display AA Normally white AA Line Defect AA Image sticking AA Color & Edge Mura AA Color crast AA Water Ripple AA Other mura(Low gray-scale white spot、S-Line Mura) TP AA Glass crack AA、OA Screen bump AA、OA Line sefects (light visible) AA Point sefects	No Display AA Abnormal Display AA Normally white AA Single line Line Defect AA Multiple lines Half-Line Image sticking AA Color & Edge Mura Color crast Water Ripple Other mura(Low gray-scale white spot、S-Line Mura) TP AA Glass crack AA Screen bump AA Color & AA Not allowed(sample(ur sample(ur sample(No Display	No Display AA	No Display		



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			0. 1 <d≤0. 25<="" th=""><th>\geq</th><th>10</th><th>2</th><th></th></d≤0.>	\geq	10	2			
			0.25 <d< td=""><td>-</td><td>_</td><td>0</td><td></td></d<>	-	_	0			
			W (mm)	L (mm)	DS (mm)	Acceptabl e number			
			W≤0.03	L<5.0	≥10	Ignore			
16	Glass scratch	AA	AA 0.03 <w≤0.05< td=""><td>L≤2.0</td><td>≥10</td><td>Ignore</td><td>Minor</td></w≤0.05<>	L≤2.0	≥10	Ignore	Minor		
	Olass scratch	74	0.00 < 0.00	2.0 <l≤5.0< td=""><td>≥10</td><td>2</td><td>Willion</td></l≤5.0<>	≥10	2	Willion		
			0.05 <w< td=""><td>-</td><td>0</td><td>0</td><td></td></w<>	-	0	0			
				L>5.0	0	0			
17	Frit Encapsulation	FA	Frit width unif	ormity. It sho breaka		oubble or	Major		
18	Polarizer crease / indentation	AA		See limit s	ample		Minor		
19	Protective film starved/overflow glue/burr	Except AA	No	No control under W≤0.3mm					
20	Polarizer bump point	Whole area	Bump:D≤0.25mr or See limi		m Al	low 3	Minor		
21	Polarizer bubble line	Out of AA, ≤0.25m m	Encap s	•	Not	allowed	Minor		
22	Scratches on the surface of polarizer	Whole area	No harm	n subject rega	ardless of cor	itrol	Minor		
				D(mm)	DS (mm)	Acceptabl e number			
	Concave dot Black and white		Front (Encap	D≤0.1	≥10	Ignore			
23	dot Polarizer Dent/Bubble	AA	surface)	0.1< D≤0.2	≥10	3	Minor		
	Delivibubble			0.2 <d< td=""><td>≥10</td><td>0</td><td></td></d<>	≥10	0			
			Metal material foreign material	/	≥10	Not allowed			
	Polarizer Scratch/		W (mm)	L (mm)	DS (mm)	Acceptabl e number			
24	Fiber(Linear)	AA	W≤0.03	L≤5.0	≥10	Ignore	Minor		
	i ibei(Lilleai)		0.03 <w≤0.05< td=""><td>L≤2.0 2.0<</td><td>≥10 ≥10</td><td>Ignore 3</td><td></td></w≤0.05<>	L≤2.0 2.0<	≥10 ≥10	Ignore 3			
		l	l .		I	l .			



=	显 光 电 KUNSHAN	GOVISION	NOX OPTOELE	CTRONICS C	U., LI		JIFPIOIGG-00	<u> </u>	
			0.05 <w< td=""><td>-</td><td></td><td>≥10</td><td>0</td><td></td></w<>	-		≥10	0		
				L>5.0		≥10	0		
			i ne tollowing	Criterion is ap	•	bie to any	y side (unit:		
			mm) Acceptable						
0.5	Edge/Side	0.4	Z	X		Υ	number	N 4"	
25	breakage	OA				not	Harrison	Minor	
			≤T	≤2.0		nded to	<5		
				=2.0		uit Area			
		Not IC			0	r Frit			
		side		Over coating			Not allowed		
26	UV glue	IC side	The coating of POL.	of IC side is no	t high	er than	Not allowed	Minor	
		IC side		of IC side is no	t high	er than	Not		
		IC and	POL.	should not hav	o bro	akaga ar	allowed		
		FPC	The coating s	should Hot Hav	e brea	anaye or	DUDDIE.		
		bondin	The coating is	s not higher th	an PC	DL.			
		g area							
	Tuffy glue	Other		not allowed to			ne diameter	Minor	
27	, 9.00	area		not more than					
		IC	Not allowed	s not higher th	an PC	<i>)</i> L.			
				the width is no	ot mor	e than 1r	mm	-	
		FPC		diameter is no					
20	Rear	EDC.	The width is r	not more than	1mm			Mircon	
28	reinforcement glue of FPC	FPC		lower than LT				Minor	
	gide of 110		The length of	attachment is	more	than bot	h ends of		
			FPC, which s	hould be rang	e fron	n 0.2 to 1			
00	105	Bondin		ond the edge of			h 0/0	N Alias	
29	ACF	g Area		width of wiring pared with the				Minor	
			FPC.	pared with the	widti	i oi tile gt	Jid IIIIgel Ul		
				ubble or wrinkl	e.				
			The compone	ent can not rev	erse	polarity			
			No wrong ins						
			FPC should not have serious crease which destroy the line, prick and spots damage. Scratch is not allowed if						
			Cu layer is ex		e. Sc	raten is n	ot allowed if		
30	FPCA	FPC			be o	kidized s	craped	Minor	
			The gold fingers should not be oxidized, scraped, folded, impressed, broken, spotted or dissymmetry.						
			Make sure FF	PC is not scale	led, w	ith its loc			
				ficiency or ob					
			The compone	ent of FPC sho	uld b	e the san	ne as BOM		



		list.			
			No remaining soldering Sn		
			No visual particle on the pad line		
			Bubble: Visible bubble is not allowed		
	FPC bonding	Bondin	Overhang: The size above 1/2 of soldering electrode	Minor	
31	FFC boliding	g area	of the parts overhang to the LAND is prohibited. The tilt		
		g area	height less than 0.5mm between FPC and foam.		
	FPC Skew		Not allowed		
			Products should put into the anti-static trays, with		
			non-overlapping, and the trays should be staggered		
			placed.		
			Different products cannot be mixed into the same inner	er Minor	
32	Package	Other	package.		
	1 dokage		The package should not have obvious deformation or	IVIIIIOI	
			breakage .The printing labels type and quantity are		
			correct.		
	The package should have QC signature. ROF		The package should have QC signature. ROHS label is		
			needed if the product is under ROHS control.		

Inspection standard for cover

	ection standard for d	over	7							
No	Item	Area	Criterion of Defect			Defec t type				
33	Cover dot、Black and white dot、 Polarizer	Whole area	D (mm)		DS (mm)	Acceptable number				
			D≤0.15mm		1	Ignore (specks is not allowed)	Minor			
	Dent/Bubble		0.15mm < D < 0.25mm		DS≥10mm	2				
	20110200010		D>0.25mm		1	Not allowed	1			
			Specks: D	<0.15mm, N	1>5 in 10mm*	10mm area	1			
	Cover Scratch/ Fiber(Linear)	AA	W(mm)	L(mm)	DS(mm)	Acceptable number				
34						W≤0.03mm	L≪10mm	≥10	Ignore	
			0.03mm < W	L≪5.0mm	≥10	2	Minor			
			AA	≤0.05mm				IVIII IOI		
"			W>0.05	/	/	Not				
				<u> </u>		allowed				
						/	L>5.0mm	/	Not	
\				Not allowe	d to scratch	allowed				
			D	DS (mm)	Acceptable					
35	Edge pinhole	Edge of cover	(mm)		number	pare.				
			D<	DS≽	one is		Minor			
			0.1mm	10mm	allowed on each side		IVIIIIOI			



羀	国 显 光 电 KUNSHAN GOVISIONOX OPTOELECTRONICS CO., LTD G1601FP161GG-001						<u>)1 </u>
			W (B or D)		L(A or C)	Acceptable number	
			W≤0.15mm		L≤3mm	≤2	
36 Uneven edge of the ink		Edge of cover	— A — — C —				Minor
			R - D -				
37	ink silk screen serrated	OA area	, , ,	D (mm) DS (mm)		Acceptable number	Minor
			D≤0.2	alı: D	DS≥10mm	2	
38	Camera Hole	OA area	breakage or crack: D≤ 0.1mm Hole is not round: Refer to the limit sample Dot Defect: D≤0.1mm, and N≤1, heterochrosis and line defect are not allowed; Camera hole smudge:not allowed		cas	인쇄물링 se 2	Minor
39	Printing defect	OA area	Wrongly Missing Ghosting and incomplete printing: not allowed Fonts consistent with the standard characters, no significant difference in visualization Penetrating scratch is not allowed			Minor	
			DS(mm)		ceptable		
	IR Hole/ Black spots/ Line scratch foreign matter/ Residue			number			5
			DS<0.1	Ignoi	re	● 黑	1
			0.1≤DS≤0.15	1			
40		OA	Note: Not visible on black background, don't affect the				
40		area	transmission rate Foreign body, dirty in IR hole: not allowed				
			Scratched\Line defects in IR hole: W \leq 0.03mm, L \leq				
			1mm, N≤1, Not visible on black background, don't				
			affect the transmission rate.				
			Residual glue in IR hole: not allowed				
	_	OA	Raised height<0.15mm, and the area is less than 25%				
41	Cover lens	area	of the entire non-display area in the cover lens				Minor
	deformation	AA area	Deformation is not allowed in AA area				



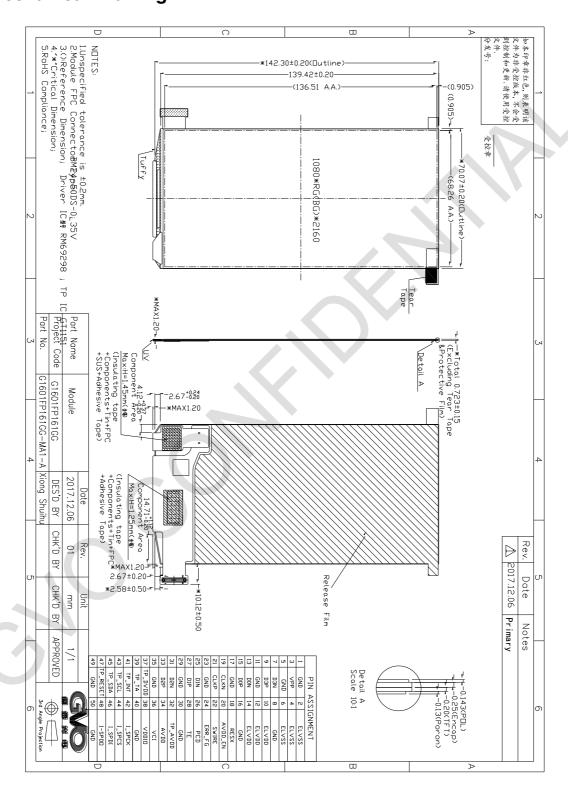
42	Poor penetration of icons	OA area	DS≤0.15 and N≤1	Minor	
43	Cover dirt	Whole			
44	Cover crack	area	Not allowed	Fatal	
45	Cover paint chips			flaw	
46	Burr Edg		L≤0.05mm, W<0.2mm accept (The premise does not		
		cover	affect the assembly and function and user operation)	Minor	
47	colour difference	OA	No significant difference in visualization (refer to the limit sample if necessary)		
		area	Not allowed in AA area		
48	Overfill	Whole area	The visible part of the periphery can not be seen after assembly, and can not affect the assembly	Minor	
			Film position deviation≤0.15mm		
49	Protective film	Whole	Scratch: no control when don't damage the body		
75	1 TOLOGIVE IIIII	area	Overfill/ lack of plastic/ Burr: no control		
			Not control the bubble inside the cover protection film		
		Cover	Function failure\ damaged\ Missing label: not allowed		
50 Easy to tear		surface	Wrinkle\ Convex-concave point\dirty\ punching\burr\ squeeze out: not control		
			Don't go beyond the edge of panel.		
			Folds\ Light leakage\ Impact assembly or thickness:		
			not allowed	Minor	
			Damaged: not allowed		
			Bump does not affect the assembly: not control	- - - Minor	
	Composite tape	I TDO	Punching the bad size meet the drawings		
51		LTPS	requirements: not control Non-wipe dirty\foreign body: not allowed		
			Foreign objects in accordance with the standard		
			line/point		
			Burr does not exceed the screen edge: not control		
			Do not have obvious bubbles		
			Gumflower\Overfill: no control		
52	Film warpage	Whole area	Warpage ≤0.2mm		
F2	ICON hala	OA	chromatic aberration, double image, dot defect, line		
53	ICON hole	area	defect: not allowed (or refer to limited sample)		
		ece hole OA area	left-right asymmetry, Hole Rather large/small or off		
54	Earpiece hole		normal(Out of specification)No chamfer, Uneven		
			polishing: not allowed	Minor	
55	Ink bumps	OA area	Positive side reference point defects; The back side does not affect the assembly; Ink overflow or		



			accumulation: not allowed					
56 Cover concave convex point		Whole	Front : Height & depth ≤ 0.15mm, size ≤ 0.4mm, if					
		area	necessary reference limit sample Back: Don't affect the fit process is not controlled					
57	Insulation Tape	Bondin g area		Obvious wrinkles and bubbles: not allowed				
		Compo	Scratch/ Gumflower: not control					
			Non-wipe dirty: not allowed					
37		nent	Offset can n		e edge of the p		Minor	
		area			to the drawing	S		
		arca			fill: not control			
					missing paste:			
			X	Y	Z	D Accepta		
						S ble		
			X<0.2mm	Y<0.2mm	Z≤1/2t	D Unilatera		
	Cover edge/side breakage		A <0.2mm	Y<0.2mm	Z≤1/2t	$\begin{vmatrix} D \\ S \end{vmatrix} \leq 2$	1	
						5		
						m		
58						m	Minor	
			X>0.2mm		/	not allowed		
			1	Y>0.2mm	/	not allowed		
			/	/	Z>1/2T	not allowed		
					X	, Y		
			Cracks are					
			not allowed					
59	Blunt	Whole		Not	allowed		Fatal	
		area			flaw			
60	Fit bubble	AA	According to the punctate specifications			Minor		
61	Vision area edge	OA	D≤0.2mm, DS>10,N≤2 (hole saw tusk less than 2),				Minor	
	defect	J/ 1	if necessary reference limit sample.					
62	Cover heterochrosis	OA	Heterochrosis side execute according to point defect size, bulk/stick refer to Limited sample			Minor		



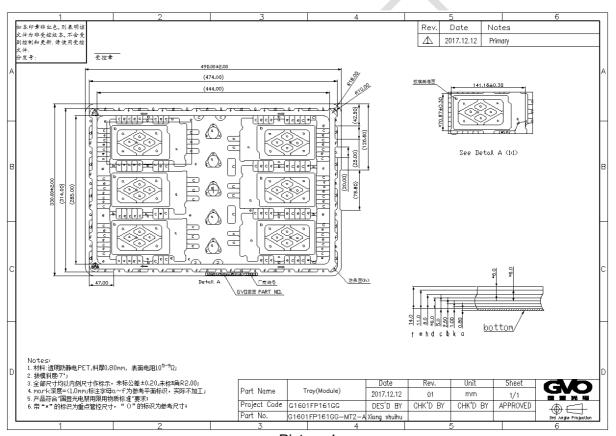
10 Mechanical Drawing





₩ **UNSHAN GOVISIONOX OPTOELECTRONICS CO., LTD** G1601FP161GG-001 Packing Drawing

Packing Condition	Contents		
Packing Type	TRAY + Carton packing type		
TRAY material model	tray (10⁵~10 ⁹ Ω)		
Tray packing type	See the picture 1		
Number of panels per tray	6 pieces		
Number of Tray per carton	24units ((22 units + 2empty)PET tray)		
Number of panels per carton	132 pieces		



Picture 1



11 Precautions for Use of AMOLED Modules

- 11.1 Handling Precautions:
- 11.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from height.
- 11.1.2 Do not press down the screen on the adjoining areas too hard because the color tone may be shifted.
- 11.1.3 The polarizer covering the display surface of the AMOLED module is soft and easily scratched. Handle this polarizer carefully.
- 11.1.4 If the display surface is contaminated, blow on the surface and gently wipe it with a soft dry cloth. If it is still not completely clear, moisten the cloth with ethyl alcohol.
- 11.1.5 Solvents may damage the polarizer. Do not use water, ketone or aromatic solvents except ethyl alcohol.Do not attempt to disassemble the AMOLED Module.
- 11.1.6 If the logic circuit power is off, do not apply the input signals.
- 11.1.7 To prevent destruction from static electricity, be careful to maintain an optimum working environment.
- 11.1.8 Be sure to make yourself in contact with the ground when handling with the AMOLED Modules.
- 11.1.9 Tools required for assembly, such as soldering irons, must be properly ground.
- 11.1.10 To reduce the generation of static electricity, do not conduct assembly or other work under dry conditions.
- 11.1.11 To protect the display surface, the AMOLED Module is coated with a film. Be careful when peeling off this protective film, because static electricity may generate.
- 11.2 Storage Precautions:
- 11.2.1 When storing the AMOLED modules, be sure that they are not directly exposed to the sunlight or the light of fluorescent lamps.
- 11.2.2 The AMOLED modules should be stored under the storage temperature range. If the AMOLED modules will be stored for a long time, the recommended condition is: Temperature: 0°C~40°C Relatively humidity: ≤80%
- 11.2.3 The AMOLED modules should be stored in the room without acid, alkali or harmful gas.
- 11.3 Transportation Precautions:
- 11.3.1 The AMOLED modules should not be suffered from falling and violent shocking during transportation. Besides, excessive press, water, damp and sunshine, should be avoided.